

Electronic Acknowledgement Receipt

EFS ID:	3387509
Application Number:	10580361
International Application Number:	
Confirmation Number:	1718
Title of Invention:	Production Of Semiconductor Substrates With Buried Layers By Joining (Bonding) Semiconductor Wafers
First Named Inventor/Applicant Name:	Roy Knechtel
Customer Number:	29673
Filer:	Richard C. Stevens/Judith Damewood
Filer Authorized By:	Richard C. Stevens
Attorney Docket Number:	LEO 003 PA
Receipt Date:	02-JUN-2008
Filing Date:	18-APR-2007
Time Stamp:	14:28:54
Application Type:	U.S. National Stage under 35 USC 371

Payment information:

Submitted with Payment	no
------------------------	----

File Listing:

Document Number	Document Description	File Name	File Size(Bytes) /Message Digest	Multi Part /zip	Pages (if appl.)
1	Power of Attorney	LEO003PA_Power_of_Attorney.pdf	135291 0710d89e70d52e3e42c31121a1edfc98 57fa705a	no	1

Warnings:

Information:

2	Assignee showing of ownership per 37 CFR 3.73(b).	LEO003PA_Statement.pdf	248361 date0256a7defa0ce211559a77be4b7b 09b6c3a	no	2
Warnings:					
Information:					
3	Information Disclosure Statement Letter	LEO003PA_Supplemental_I DS_cover.pdf	39611 77d009abe1a406ca962344c845a04cb 0d0911a5	no	2
Warnings:					
Information:					
4	Information Disclosure Statement (IDS) Filed	LEO003PA_Supplemental_I DS_SB08B.pdf	122709 1e101e55239c5d1a7b247c444fb9 c0b-f511	no	1
Warnings:					
Information:					
This is not an USPTO supplied IDS fillable form					
5	NPL Documents	LEO003PA_SemiconductorWaferBonding_Part1_NPL.pdf	20134789 1eeb5e0243599fc2d19128fddd2724 e327e7d	no	80
Warnings:					
Information:					
6	NPL Documents	LEO003PA_SemiconductorWaferBonding_Part2_NPL.pdf	23151027 60541943767f490483925f7c75b5ca 0c22395	no	80
Warnings:					
Information:					
Total Files Size (in bytes): 43831788					
This Acknowledgement Receipt evidences receipt on the noted date by the USPTO of the indicated documents, characterized by the applicant, and including page counts, where applicable. It serves as evidence of receipt similar to a Post Card, as described in MPEP 503.					
New Applications Under 35 U.S.C. 111 If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.					
National Stage of an International Application under 35 U.S.C. 371 If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.					
New International Application Filed with the USPTO as a Receiving Office If a new international application is being filed and the international application includes the necessary components for an international filing date (see PCT Article 11 and MPEP 1810), a Notification of the International Application Number and of the International Filing Date (Form PCT/RO/105) will be issued in due course, subject to prescriptions concerning national security, and the date shown on this Acknowledgement Receipt will establish the international filing date of the application.					